

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY AGREEMENT

CONVEYING PARTY DATA

Name	Execution Date
GM Global Technology Operations, Inc.	04/09/2009

RECEIVING PARTY DATA

Name:	Citicorp USA, Inc. as agent for Bank Priority Secured Parties
Street Address:	Two Penns Way, Suite 200
City:	New Castle
State/Country:	DELAWARE
Postal Code:	19720

Name:	Citicorp USA, Inc. as agent for Hedge Priority Secured Parties
Street Address:	Two Penns Way, Suite 200
City:	New Castle
State/Country:	DELAWARE
Postal Code:	19720

PROPERTY NUMBERS Total: 1000

Property Type	Number
Application Number:	10723306
Application Number:	10724911
Application Number:	10724948
Application Number:	10725065
Application Number:	10725213
Application Number:	10725680
Application Number:	10730436
Application Number:	10730440
Application Number:	10730569
Application Number:	10730590

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Application Number:	10730642
Application Number:	10730731
Application Number:	10732500
Application Number:	10732713
Application Number:	10733720
Application Number:	10734094
Application Number:	10735599
Application Number:	10736930
Application Number:	10737501
Application Number:	10737508
Application Number:	10737509
Application Number:	10737510
Application Number:	10738344
Application Number:	10738345
Application Number:	10738402
Application Number:	10738476
Application Number:	10738481
Application Number:	10738564
Application Number:	10738565
Application Number:	10738566
Application Number:	10738766
Application Number:	10738880
Application Number:	10739356
Application Number:	10739363
Application Number:	10739432
Application Number:	10739435
Application Number:	10739462
Application Number:	10739463
Application Number:	10739609
Application Number:	10739615
Application Number:	10739616
Application Number:	10739789
Application Number:	10739790
Application Number:	10739793
Application Number:	10739830

Application Number:	10745135
Application Number:	10748660
Application Number:	10751865
Application Number:	10752133
Application Number:	10752144
Application Number:	10752286
Application Number:	10752603
Application Number:	10753024
Application Number:	10755128
Application Number:	10755486
Application Number:	10755488
Application Number:	10755801
Application Number:	10755841
Application Number:	10755949
Application Number:	10756664
Application Number:	10756729
Application Number:	10756942
Application Number:	10758816
Application Number:	10760961
Application Number:	10762403
Application Number:	10762404
Application Number:	10762651
Application Number:	10762656
Application Number:	10763514
Application Number:	10763564
Application Number:	10763629
Application Number:	10763633
Application Number:	10763663
Application Number:	10763666
Application Number:	10763937
Application Number:	10763951
Application Number:	10764014
Application Number:	10765239
Application Number:	10765240
Application Number:	10765690

Application Number:	10765815
Application Number:	10765822
Application Number:	10766100
Application Number:	10766155
Application Number:	10766156
Application Number:	10768299
Application Number:	10768384
Application Number:	10768507
Application Number:	10768538
Application Number:	10768541
Application Number:	10768622
Application Number:	10768723
Application Number:	10770863
Application Number:	10770876
Application Number:	10770933
Application Number:	10771171
Application Number:	10771172
Application Number:	10771207
Application Number:	10771279
Application Number:	10771842
Application Number:	10771917
Application Number:	10772000
Application Number:	10772604
Application Number:	10772699
Application Number:	10772845
Application Number:	10772849
Application Number:	10772850
Application Number:	10772872
Application Number:	10772994
Application Number:	10774964
Application Number:	10774969
Application Number:	10775452
Application Number:	10775462
Application Number:	10775648
Application Number:	10776556

Application Number:	10779362
Application Number:	10779463
Application Number:	10779481
Application Number:	10779514
Application Number:	10779530
Application Number:	10779531
Application Number:	10779558
Application Number:	10780025
Application Number:	10780382
Application Number:	10780481
Application Number:	10780487
Application Number:	10780488
Application Number:	10780489
Application Number:	10780490
Application Number:	10781276
Application Number:	10781429
Application Number:	10781430
Application Number:	10781452
Application Number:	10782159
Application Number:	10782190
Application Number:	10782520
Application Number:	10783405
Application Number:	10784344
Application Number:	10784354
Application Number:	10784555
Application Number:	10784560
Application Number:	10784641
Application Number:	10785508
Application Number:	10785509
Application Number:	10785654
Application Number:	10785691
Application Number:	10785694
Application Number:	10785792
Application Number:	10785793
Application Number:	10786638

Application Number:	10786639
Application Number:	10786642
Application Number:	10786832
Application Number:	10786841
Application Number:	10786842
Application Number:	10787292
Application Number:	10787381
Application Number:	10787419
Application Number:	10787431
Application Number:	10787617
Application Number:	10788155
Application Number:	10788804
Application Number:	10788929
Application Number:	10788931
Application Number:	10789514
Application Number:	10789899
Application Number:	10791428
Application Number:	10793487
Application Number:	10793491
Application Number:	10794012
Application Number:	10794939
Application Number:	10795479
Application Number:	10795615
Application Number:	10797228
Application Number:	10797461
Application Number:	10797671
Application Number:	10797861
Application Number:	10797862
Application Number:	10797864
Application Number:	10797865
Application Number:	10797954
Application Number:	10799068
Application Number:	10799979
Application Number:	10801780
Application Number:	10801784

Application Number:	10801790
Application Number:	10802196
Application Number:	10802454
Application Number:	10803614
Application Number:	10803799
Application Number:	10806674
Application Number:	10806676
Application Number:	10807593
Application Number:	10807600
Application Number:	10807675
Application Number:	10807696
Application Number:	10807705
Application Number:	10807751
Application Number:	10807768
Application Number:	10807769
Application Number:	10807803
Application Number:	10807829
Application Number:	10807831
Application Number:	10807832
Application Number:	10807886
Application Number:	10808072
Application Number:	10808074
Application Number:	10808081
Application Number:	10808082
Application Number:	10808977
Application Number:	10808978
Application Number:	10809057
Application Number:	10809058
Application Number:	10809059
Application Number:	10810983
Application Number:	10811084
Application Number:	10811161
Application Number:	10811204
Application Number:	10811377
Application Number:	10812438

Application Number:	10812466
Application Number:	10812467
Application Number:	10812584
Application Number:	10813580
Application Number:	10813898
Application Number:	10813900
Application Number:	10815332
Application Number:	10815383
Application Number:	10817082
Application Number:	10818467
Application Number:	10819399
Application Number:	10819401
Application Number:	10819402
Application Number:	10819410
Application Number:	10819418
Application Number:	10819436
Application Number:	10819446
Application Number:	10819448
Application Number:	10819449
Application Number:	10819724
Application Number:	10822900
Application Number:	10823170
Application Number:	10823305
Application Number:	10823391
Application Number:	10824032
Application Number:	10824406
Application Number:	10824876
Application Number:	10826200
Application Number:	10826893
Application Number:	10827115
Application Number:	10827699
Application Number:	10827721
Application Number:	10827731
Application Number:	10827753
Application Number:	10828074

Application Number:	10828420
Application Number:	10828421
Application Number:	10828422
Application Number:	10828595
Application Number:	10828757
Application Number:	10830156
Application Number:	10830493
Application Number:	10830945
Application Number:	10830946
Application Number:	10831335
Application Number:	10831655
Application Number:	10831734
Application Number:	10831764
Application Number:	10831765
Application Number:	10833335
Application Number:	10833343
Application Number:	10833731
Application Number:	10833910
Application Number:	10833911
Application Number:	10833916
Application Number:	10833918
Application Number:	10836643
Application Number:	10836655
Application Number:	10836658
Application Number:	10836660
Application Number:	10836795
Application Number:	10836799
Application Number:	10836893
Application Number:	10837875
Application Number:	10837927
Application Number:	10837936
Application Number:	10838084
Application Number:	10838606
Application Number:	10838607
Application Number:	10838608

Application Number:	10841283
Application Number:	10842788
Application Number:	10842789
Application Number:	10843013
Application Number:	10843080
Application Number:	10843228
Application Number:	10843516
Application Number:	10843903
Application Number:	10845904
Application Number:	10845994
Application Number:	10845995
Application Number:	10845999
Application Number:	10846000
Application Number:	10846001
Application Number:	10846013
Application Number:	10846014
Application Number:	10846016
Application Number:	10846017
Application Number:	10846018
Application Number:	10846139
Application Number:	10846141
Application Number:	10846142
Application Number:	10846143
Application Number:	10846144
Application Number:	10846153
Application Number:	10847719
Application Number:	10847796
Application Number:	10848203
Application Number:	10848701
Application Number:	10850550
Application Number:	10850724
Application Number:	10850725
Application Number:	10850752
Application Number:	10850762
Application Number:	10850765

Application Number:	10850767
Application Number:	10850768
Application Number:	10850769
Application Number:	10851000
Application Number:	10851034
Application Number:	10851035
Application Number:	10851045
Application Number:	10851351
Application Number:	10851391
Application Number:	10851394
Application Number:	10851395
Application Number:	10851402
Application Number:	10851695
Application Number:	10852425
Application Number:	10852446
Application Number:	10852560
Application Number:	10852601
Application Number:	10853406
Application Number:	10853430
Application Number:	10853440
Application Number:	10853739
Application Number:	10853903
Application Number:	10854290
Application Number:	10854359
Application Number:	10859396
Application Number:	10860628
Application Number:	10861183
Application Number:	10861190
Application Number:	10861326
Application Number:	10861633
Application Number:	10862072
Application Number:	10862557
Application Number:	10863015
Application Number:	10863956
Application Number:	10864670

Application Number:	10864716
Application Number:	10864717
Application Number:	10864724
Application Number:	10864783
Application Number:	10867401
Application Number:	10867402
Application Number:	10867584
Application Number:	10868187
Application Number:	10868192
Application Number:	10868205
Application Number:	10868696
Application Number:	10869136
Application Number:	10871760
Application Number:	10872228
Application Number:	10872327
Application Number:	10872726
Application Number:	10873926
Application Number:	10873933
Application Number:	10874088
Application Number:	10874089
Application Number:	10874090
Application Number:	10874091
Application Number:	10874092
Application Number:	10874107
Application Number:	10874115
Application Number:	10874120
Application Number:	10875464
Application Number:	10876130
Application Number:	10877496
Application Number:	10877937
Application Number:	10878336
Application Number:	10878709
Application Number:	10880225
Application Number:	10881207
Application Number:	10881213

Application Number:	10881214
Application Number:	10883168
Application Number:	10886722
Application Number:	10886823
Application Number:	10887746
Application Number:	10888489
Application Number:	10891288
Application Number:	10891292
Application Number:	10891303
Application Number:	10891324
Application Number:	10891462
Application Number:	10891469
Application Number:	10891473
Application Number:	10891474
Application Number:	10893118
Application Number:	10893119
Application Number:	10893758
Application Number:	10895249
Application Number:	10895640
Application Number:	10895641
Application Number:	10895642
Application Number:	10897668
Application Number:	10897895
Application Number:	10897969
Application Number:	10898144
Application Number:	10898405
Application Number:	10898442
Application Number:	10898570
Application Number:	10898635
Application Number:	10899210
Application Number:	10899211
Application Number:	10899212
Application Number:	10899395
Application Number:	10899442
Application Number:	10899443

Application Number:	10899445
Application Number:	10899446
Application Number:	10899456
Application Number:	10899457
Application Number:	10899716
Application Number:	10899978
Application Number:	10900479
Application Number:	10900480
Application Number:	10900593
Application Number:	10900751
Application Number:	10901646
Application Number:	10901656
Application Number:	10901673
Application Number:	10901711
Application Number:	10901721
Application Number:	10901722
Application Number:	10901723
Application Number:	10902339
Application Number:	10902472
Application Number:	10903167
Application Number:	10903912
Application Number:	10903928
Application Number:	10903929
Application Number:	10909164
Application Number:	10909250
Application Number:	10909265
Application Number:	10910066
Application Number:	10910232
Application Number:	10911851
Application Number:	10911889
Application Number:	10912016
Application Number:	10912296
Application Number:	10912298
Application Number:	10912396
Application Number:	10912618

Application Number:	10912620
Application Number:	10913153
Application Number:	10913690
Application Number:	10913691
Application Number:	10913722
Application Number:	10913860
Application Number:	10913933
Application Number:	10913934
Application Number:	10913966
Application Number:	10914018
Application Number:	10914362
Application Number:	10914875
Application Number:	10915236
Application Number:	10915986
Application Number:	10916120
Application Number:	10917038
Application Number:	10917066
Application Number:	10918581
Application Number:	10918583
Application Number:	10918615
Application Number:	10918620
Application Number:	10918621
Application Number:	10918653
Application Number:	10918654
Application Number:	10918740
Application Number:	10920657
Application Number:	10920838
Application Number:	10920997
Application Number:	10921005
Application Number:	10921237
Application Number:	10921241
Application Number:	10921514
Application Number:	10922768
Application Number:	10922773
Application Number:	10923422

Application Number:	10923427
Application Number:	10924317
Application Number:	10924498
Application Number:	10924499
Application Number:	10924557
Application Number:	10924639
Application Number:	10925053
Application Number:	10925753
Application Number:	10925754
Application Number:	10925755
Application Number:	10925757
Application Number:	10925758
Application Number:	10925849
Application Number:	10925853
Application Number:	10926177
Application Number:	10926178
Application Number:	10926632
Application Number:	10926748
Application Number:	10927348
Application Number:	10929190
Application Number:	10929207
Application Number:	10929273
Application Number:	10929274
Application Number:	10930324
Application Number:	10930325
Application Number:	10930426
Application Number:	10930427
Application Number:	10930464
Application Number:	10930530
Application Number:	10930531
Application Number:	10931135
Application Number:	10931464
Application Number:	10933679
Application Number:	10933682
Application Number:	10935452

Application Number:	10936976
Application Number:	10937087
Application Number:	10937088
Application Number:	10938494
Application Number:	10939548
Application Number:	10939549
Application Number:	10939551
Application Number:	10939552
Application Number:	10939553
Application Number:	10940523
Application Number:	10940538
Application Number:	10940539
Application Number:	10942542
Application Number:	10944576
Application Number:	10945937
Application Number:	10946138
Application Number:	10946701
Application Number:	10946760
Application Number:	10946915
Application Number:	10947569
Application Number:	10948402
Application Number:	10948403
Application Number:	10948559
Application Number:	10948613
Application Number:	10948630
Application Number:	10948974
Application Number:	10950837
Application Number:	10951417
Application Number:	10951421
Application Number:	10951539
Application Number:	10951540
Application Number:	10952022
Application Number:	10952200
Application Number:	10953657
Application Number:	10953778

Application Number:	10953783
Application Number:	10953954
Application Number:	10953956
Application Number:	10953957
Application Number:	10956653
Application Number:	10960123
Application Number:	10960472
Application Number:	10960484
Application Number:	10960489
Application Number:	10960552
Application Number:	10960860
Application Number:	10960880
Application Number:	10961277
Application Number:	10961451
Application Number:	10961691
Application Number:	10961692
Application Number:	10961693
Application Number:	10961694
Application Number:	10961698
Application Number:	10961813
Application Number:	10961868
Application Number:	10961983
Application Number:	10962651
Application Number:	10962802
Application Number:	10963248
Application Number:	10963672
Application Number:	10964138
Application Number:	10964176
Application Number:	10965358
Application Number:	10965379
Application Number:	10965389
Application Number:	10965416
Application Number:	10965509
Application Number:	10965510
Application Number:	10965618

Application Number:	10965671
Application Number:	10965674
Application Number:	10966548
Application Number:	10967780
Application Number:	10967795
Application Number:	10967889
Application Number:	10968494
Application Number:	10968591
Application Number:	10968592
Application Number:	10968852
Application Number:	10970787
Application Number:	10972845
Application Number:	10972854
Application Number:	10973689
Application Number:	10973697
Application Number:	10974303
Application Number:	10975890
Application Number:	10975891
Application Number:	10975892
Application Number:	10976053
Application Number:	10976054
Application Number:	10978504
Application Number:	10978790
Application Number:	10978979
Application Number:	10978980
Application Number:	10978981
Application Number:	10978982
Application Number:	10978990
Application Number:	10979005
Application Number:	10979006
Application Number:	10979016
Application Number:	10981847
Application Number:	10981848
Application Number:	10981867
Application Number:	10981971

Application Number:	10982304
Application Number:	10983329
Application Number:	10983330
Application Number:	10984011
Application Number:	10984178
Application Number:	10984269
Application Number:	10984386
Application Number:	10984672
Application Number:	10987057
Application Number:	10987131
Application Number:	10987132
Application Number:	10987173
Application Number:	10987314
Application Number:	10987461
Application Number:	10987523
Application Number:	10987556
Application Number:	10987609
Application Number:	10988324
Application Number:	10990936
Application Number:	10991617
Application Number:	10992529
Application Number:	10992530
Application Number:	10992603
Application Number:	10995844
Application Number:	10995846
Application Number:	10995908
Application Number:	10995909
Application Number:	10995911
Application Number:	10995913
Application Number:	10996095
Application Number:	10996185
Application Number:	10997456
Application Number:	10997459
Application Number:	10997475
Application Number:	10997476

Application Number:	10997661
Application Number:	10997710
Application Number:	11001708
Application Number:	11001709
Application Number:	11002371
Application Number:	11002389
Application Number:	11002569
Application Number:	11002815
Application Number:	11004666
Application Number:	11007335
Application Number:	11007631
Application Number:	11007871
Application Number:	11007872
Application Number:	11008089
Application Number:	11008302
Application Number:	11008419
Application Number:	11008424
Application Number:	11008427
Application Number:	11009374
Application Number:	11009378
Application Number:	11009403
Application Number:	11009404
Application Number:	11009405
Application Number:	11009417
Application Number:	11009525
Application Number:	11009526
Application Number:	11009527
Application Number:	11009528
Application Number:	11009968
Application Number:	11010552
Application Number:	11011234
Application Number:	11013647
Application Number:	11017173
Application Number:	11017266
Application Number:	11017267

Application Number:	11017348
Application Number:	11017362
Application Number:	11017363
Application Number:	11017364
Application Number:	11017366
Application Number:	11017368
Application Number:	11017388
Application Number:	11017411
Application Number:	11017412
Application Number:	11017413
Application Number:	11017420
Application Number:	11018621
Application Number:	11018661
Application Number:	11019009
Application Number:	11019036
Application Number:	11019061
Application Number:	11026345
Application Number:	11026346
Application Number:	11027794
Application Number:	11028820
Application Number:	11028837
Application Number:	11028843
Application Number:	11028886
Application Number:	11028887
Application Number:	11028893
Application Number:	11028912
Application Number:	11029075
Application Number:	11029076
Application Number:	11029889
Application Number:	11029890
Application Number:	11030357
Application Number:	11031059
Application Number:	11031363
Application Number:	11031397
Application Number:	11032551

Application Number:	11032552
Application Number:	11032789
Application Number:	11032790
Application Number:	11032791
Application Number:	11034023
Application Number:	11035163
Application Number:	11035183
Application Number:	11035184
Application Number:	11035338
Application Number:	11035343
Application Number:	11035344
Application Number:	11035345
Application Number:	11035390
Application Number:	11035416
Application Number:	11036213
Application Number:	11036776
Application Number:	11039571
Application Number:	11039572
Application Number:	11040617
Application Number:	11040642
Application Number:	11040666
Application Number:	11041614
Application Number:	11041635
Application Number:	11041664
Application Number:	11041749
Application Number:	11041795
Application Number:	11041802
Application Number:	11043221
Application Number:	11043222
Application Number:	11043274
Application Number:	11043341
Application Number:	11043706
Application Number:	11043722
Application Number:	11046572
Application Number:	11047314

Application Number:	11047436
Application Number:	11047508
Application Number:	11049001
Application Number:	11049213
Application Number:	11049373
Application Number:	11049448
Application Number:	11049555
Application Number:	11049626
Application Number:	11049832
Application Number:	11050596
Application Number:	11052461
Application Number:	11053061
Application Number:	11053062
Application Number:	11053434
Application Number:	11053489
Application Number:	11053555
Application Number:	11053633
Application Number:	11053687
Application Number:	11053693
Application Number:	11053714
Application Number:	11053740
Application Number:	11053966
Application Number:	11053989
Application Number:	11053990
Application Number:	11054240
Application Number:	11054241
Application Number:	11054481
Application Number:	11054483
Application Number:	11054570
Application Number:	11054571
Application Number:	11054677
Application Number:	11054678
Application Number:	11054679
Application Number:	11055370
Application Number:	11055390

Application Number:	11055391
Application Number:	11055468
Application Number:	11057612
Application Number:	11058072
Application Number:	11058100
Application Number:	11058138
Application Number:	11058503
Application Number:	11058574
Application Number:	11059820
Application Number:	11059877
Application Number:	11059878
Application Number:	11059905
Application Number:	11059906
Application Number:	11060050
Application Number:	11060068
Application Number:	11060075
Application Number:	11060076
Application Number:	11060083
Application Number:	11060217
Application Number:	11060225
Application Number:	11060226
Application Number:	11060227
Application Number:	11060942
Application Number:	11060947
Application Number:	11060948
Application Number:	11060950
Application Number:	11060973
Application Number:	11061105
Application Number:	11061106
Application Number:	11061114
Application Number:	11061130
Application Number:	11061131
Application Number:	11061132
Application Number:	11061134
Application Number:	11061137

Application Number:	11061138
Application Number:	11061274
Application Number:	11061322
Application Number:	11062101
Application Number:	11062895
Application Number:	11063328
Application Number:	11063329
Application Number:	11063330
Application Number:	11063331
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Application Number:	11112447
Application Number:	11112599
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Application Number:	11113462
Application Number:	11113483
Application Number:	11113503
Application Number:	11113574
Application Number:	11113962
Application Number:	11115035

CORRESPONDENCE DATA

Fax Number: (248)267-4471
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 313-665-4702
Email: patrice.l.leland@gm.com
Correspondent Name: Patrice Uchno Leland
Address Line 1: P.O. Box 300
Address Line 2: Mail Code 482-C23-B21
Address Line 4: Detroit, MICHIGAN 48265-3000

ATTORNEY DOCKET NUMBER: GTO TO CITICORP SEC INT 3

NAME OF SUBMITTER: Patrice Uchno Leland

Total Attachments: 17
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INTELLECTUAL PROPERTY PLEDGE AGREEMENT

Intellectual Property Pledge Agreement (the "Junior IP Pledge Agreement"), dated as of April __, 2009, by General Motors Corporation (the "Borrower") and Annunciata Corporation, Argonaut Holdings, Inc., General Motors Asia Pacific Holdings, LLC, General Motors Asia, Inc., General Motors International Holdings, Inc., General Motors Overseas Corporation, General Motors Overseas Distribution Corporation, General Motors Product Services, Inc., General Motors Research Corporation, GM APO Holdings, LLC, GM Eurometals, Inc., GM Finance Co. Holdings LLC, GM GEFS L.P., GM Global Technology Operations, Inc., GM Global Tooling Company, Inc., GM LAAM Holdings, LLC, GM Preferred Finance Co. Holdings LLC, GM Technologies, LLC, GM-DI Leasing Corporation, GMOC Administrative Services Corporation, OnStar, LLC, Riverfront Holdings, Inc., Riverfront Holdings Phase II, Inc., Environmental Corporate Remediation Company, Inc., Grand Pointe Holdings, Inc., Remediation and Liability Management Company, Inc., GM Subsystems Manufacturing LLC, GM Global Steering Holdings LLC, Saturn Corporation ("Saturn"), and Saturn Distribution Corporation (collectively, the "Guarantors," and collectively with Borrower, the "Grantors"), in favor of Citicorp USA, Inc. as Agent (in such capacity, the "Bank Priority Representative") for the Bank Priority Secured Parties and as Agent (in such capacity, the "Hedge Priority Representative") for the Hedge Priority Secured Parties. References herein to "Agent" shall mean Citicorp USA, Inc. in its capacities as Bank Priority Representative and as Hedge Priority Representative.) (References herein to "Secured Parties" shall mean collectively the Bank Priority Secured Parties and the Hedge Priority Secured Parties).

RECITALS

Pursuant to the Amended and Restated Credit Agreement, dated as of July 20, 2006 (as amended by the First Amendment and Consent thereto, dated as of February 11, 2009, as the same may from time to time be further amended, modified or otherwise supplemented, the "Credit Agreement") among the Borrower, General Motors of Canada Limited ("GM Canada"), Saturn, the financial institutions and other entities from time to time parties thereto and Citicorp USA, Inc., as administrative agent, the Lenders have agreed to make loans and other financial accommodations to the Borrower and GM Canada upon the terms and subject to the conditions set forth therein;

The Borrower and the Guarantors are parties to the Guaranty and Security Agreement, dated as of February 11, 2009 (the "Junior Security Agreement"), in favor of the Bank Priority Representative, as agent for the Bank Priority Secured Parties, and the Hedge Priority Representative, as agent for the Hedge Priority Secured Parties, pursuant to which, among other things, the Borrower and the Guarantors are required to execute and deliver this Junior IP Pledge Agreement;

The Borrower and the Guarantors are parties to the Intercreditor Agreement, dated as of February 11, 2009 (the "Intercreditor Agreement"), with the Bank Priority Representative, as agent for the Bank Priority Secured Parties, the Hedge Priority Representative, as agent for the Hedge Priority Secured Parties, and the UST Representative; and

Accordingly, for good and valuable consideration of the premises, receipt of which by the parties hereto is hereby acknowledged, the parties hereto hereby agree as follows:

Section 1. Defined Terms

Unless otherwise defined herein, all capitalized terms used herein have the meaning given to them or provided by reference in the Credit Agreement or in the Junior Security Agreement as the context requires.

Section 2. Grant of Security Interests in IP Collateral

(a) **Grant of Bank Priority Security Interest.** As security for the prompt and complete payment when due of the Bank Priority Obligations and the performance by each Grantor of all the covenants and obligations to be performed by it pursuant to the Credit Agreement and the other Loan Documents, each Grantor, in order to secure its guaranty under the Junior Security Agreement (or, in the case of Saturn, its guaranty under the Credit Agreement), hereby mortgages, pledges, and grants to the Bank Priority Representative, for the ratable benefit of the Bank Priority Secured Parties, a Lien (having the priorities set forth in the Intercreditor Agreement and Annex A to the Junior Security Agreement) on and security interest in all of its rights, title and interest in and to the following property of such Grantor, as the case may be, whether now owned or existing or hereafter acquired or arising and regardless of where located (the "IP Collateral"):

(i) All domestic and foreign letters patent, design patents, utility patents, industrial designs, and all intellectual property rights in inventions, trade secrets, ideas, concepts, methods, techniques, processes, proprietary information, technology, know-how, formulae, and other general intangibles of like nature, now existing or hereafter acquired or owned by the Grantor (including, without limitation, all domestic and foreign letters patent, design patents, utility patents, industrial designs, inventions, trade secrets, ideas, concepts, methods, techniques, processes, proprietary information, technology, know-how and formulae described in Exhibit A hereto), all applications, registrations and recordings thereof (including, without limitation, applications, registrations and recordings in the United States Patent and Trademark Office, or in any similar office or agency of the United States or any other country or any political subdivision thereof), and all reissues, divisions, continuations, continuations in part and extensions or renewals thereof;

(ii) All domestic and foreign trademarks, service marks, collective marks, certification marks, trade dress, trade names, business names, d/b/a's, Internet domain names, trade styles, designs, logos and other source or business identifiers and all general intangibles of like nature, now or hereafter owned, adopted, or acquired by the Grantor (including, without limitation, all domestic and foreign trademarks, service marks, collective marks, certification marks, trade dress, trade names, business names, d/b/a's, Internet domain names, trade styles, designs, logos and other source or business identifiers described in Exhibit B hereto), all applications, registrations and recordings thereof (including, without limitation, applications, registrations and recordings in the United States Patent and Trademark Office or in any similar office or agency of the

United States, any state thereof or any other country or any political subdivision thereof), all reissues, extensions or renewals thereof, together with all goodwill of the business symbolized by such marks;

(iii) All domestic and foreign copyrights, whether registered or unregistered, including, without limitation, all copyright rights throughout the universe (whether now or hereafter arising), in any and all media (whether now or hereafter developed), in and to all original works of authorship (including, without limitation, all marketing materials created by or on behalf of the Grantor), acquired or owned by the Grantor (including, without limitation, all copyrights described in Exhibit C hereto) all applications, registrations and recordings thereof (including, without limitation, applications, registrations and recordings in the United States Copyright Office or in any similar office or agency of the United States or any other country or any political subdivision thereof), and all reissues, renewals, restorations, extensions or revisions thereof;

(iv) all Proceeds with respect to the foregoing clauses (i) through (iii);
and

(v) to the extent not included in the foregoing, all proceeds, products, offspring, rents, revenues, issues, profits, royalties, income, benefits, accessions, additions, substitutions and replacements of and to any and all of the foregoing;

in each case howsoever such Grantor's interest therein may arise or appear (whether by ownership, security interest, claim or otherwise); provided that, notwithstanding anything to the contrary contained herein or in any other Loan Document, the terms "IP Collateral" (as used herein) or "Additional Collateral" (as used in the Credit Agreement and the Junior Security Agreement) and each other term used in the definition thereof shall not include, and no Grantor is pledging or granting a security interest in, any Property to the extent that (a) such Property constitutes Excluded Collateral or (b) if such Grantor has not purported to grant a first lien security interest in such Property to the UST Agent; provided further, however, that if and when, and to the extent that, any Property ceases to be Excluded Collateral and the relevant Grantor has purported to grant a first lien security interest in such Property to the UST Agent, such Grantor hereby grants to the Bank Priority Representative, for the ratable benefit of the Bank Priority Creditors, and at all times from and after such date, the Bank Priority Representative shall have a Lien (having the priorities set forth in the Intercreditor Agreement and Annex A to the Junior Security Agreement) in and on such Property, and such Grantor shall cooperate in all respects to ensure the prompt perfection of the Bank Priority Representative's security interest therein.

(b) **Grant of Hedge Priority Security Interest.** As security for the prompt and complete payment when due of the Hedge Priority Obligations and the performance by each Grantor of all the covenants and obligations to be performed by it pursuant to the Credit Agreement and the other Loan Documents, each Grantor hereby mortgages, pledges and grants to the Hedge Priority Representative, for the ratable benefit of the Hedge Priority Secured Parties, a Lien on and security interest in all of its rights, title and interest in and to the IP Collateral; provided that, notwithstanding anything to the contrary contained herein or in any other Loan Document, the terms "IP Collateral" (as used herein) or "Additional Collateral" (as

used in the Credit Agreement and the Junior Security Agreement) and each other term used in the definition thereof shall not include, and no Grantor is pledging or granting a security interest in, any Property to the extent that (a) such Property constitutes Excluded Collateral or (b) if such Grantor has not purported to grant a first lien security interest in such Property to the UST Agent; provided further, however, that if and when, and to the extent that, any Property ceases to be Excluded Collateral and the relevant Grantor has purported to grant a first lien security interest in such Property to the UST Agent, such Grantor hereby grants to the Hedge Priority Representative, for the ratable benefit of the Hedge Priority Secured Parties, and at all times from and after such date, the Hedge Priority Representative shall have a Lien in and on such Property, and such Grantor shall cooperate in all respects to ensure the prompt perfection of the Hedge Priority Representative's security interest therein.

(c) **Intercreditor Provisions.**

(i) Intercreditor Matters among Secured Parties. Notwithstanding anything to the contrary herein, until the First Priority Obligations Payment Date (as defined in Annex A to the Junior Security Agreement), the rights of the Hedge Priority Secured Parties under this Junior IP Pledge Agreement shall be subject to the intercreditor provisions set forth in Annex A to the Junior Security Agreement.

(ii) Intercreditor Matters with UST Representative. Notwithstanding anything to the contrary herein, the rights of the Secured Parties under this Junior IP Pledge Agreement shall be subject to the provisions of the Intercreditor Agreement.

Section 3. Pledge Agreement

(a) THE INTERESTS IN THE IP COLLATERAL BEING ASSIGNED HEREUNDER SHALL NOT BE CONSTRUED AS A CURRENT ASSIGNMENT BUT, RATHER AS SECURITY INTERESTS THAT PROVIDE THE BANK PRIORITY SECURED PARTIES AND THE HEDGE PRIORITY SECURED PARTIES SUCH RIGHTS AS ARE PROVIDED TO HOLDERS OF SECURITY INTERESTS UNDER APPLICABLE LAW.

(b) The security interests granted pursuant to this Junior IP Pledge Agreement are granted in conjunction with the security interests granted to the Bank Priority Representative and the Hedge Priority Representative pursuant to the Junior Security Agreement and the Borrower and each of the Guarantors hereby acknowledge and affirm that the rights and remedies of the Bank Priority Representative and the Hedge Priority Representative with respect to the security interests in the IP Collateral made and granted hereby are more fully set forth in the Junior Security Agreement, the terms and provisions of which (including Annex A thereto) are incorporated by reference herein as if fully set forth herein. In the event of any conflict between the terms of the Junior Security Agreement and this Junior IP Pledge Agreement, the Junior Security Agreement shall govern.

Section 4. Authorization

To the extent applicable, the parties hereto authorize and request that the Commissioner of Patents and Trademarks of the United States record this security interest in the IP Collateral.

To the extent applicable, the parties hereto authorize and request that the Copyright Office of the United States record this security interest in the IP Collateral.

Section 5. Continuing Security Interest; Release and Discharge of Security Interest

(a) This Junior IP Pledge Agreement shall create a continuing security interest in the IP Collateral and shall (i) remain in full force and effect until released in accordance with Section 5(b) or Section 10.13 of the Credit Agreement, (ii) be binding upon and inure to the benefit of the Borrower and each Guarantor, each of their executors, administrators, successors and assigns, and (iii) inure to the benefit of and be binding upon the Bank Priority Representative and the Hedge Priority Representative and their respective successors, transferees and assigns. Upon the payment and satisfaction in full of the Secured Obligations (whether or not the Hedge Priority Obligations are paid or satisfied), the Borrower and each Guarantor shall be entitled to the return, upon its request and at its expense, of such of the IP Collateral as shall not have been sold or otherwise applied pursuant to the terms hereof.

(b) Release Provisions

(i) Release of Lien and Security Interest Upon Satisfaction of all Obligations.

(A) With respect to both of the Bank Priority Representative and the Hedge Priority Representative, upon termination of the Junior Security Agreement and the indefeasible payment in full of the Secured Obligations and the termination of the Extended Secured Commitments, each of the Bank Priority Representative and the Hedge Priority Representative shall release its Lien and security interest in the IP Collateral, (B) with respect to the Bank Priority Representative only, upon the indefeasible payment in full of the Bank Priority Obligations, the Bank Priority Representative shall release its Lien and security interest in the IP Collateral and (C) with respect to the Hedge Priority Representative only, upon the indefeasible payment in full of the Hedge Priority Obligations, the Hedge Priority Representative shall release its Lien and security interest in the IP Collateral; provided in each case that if any payment, or any part thereof, of any of the Credit Agreement Obligations is rescinded or must otherwise be restored or returned by any Secured Party upon the insolvency, bankruptcy, dissolution, liquidation or reorganization of the Borrower and/or any Guarantor or upon or as a result of the appointment of a receiver, intervenor or conservator of, or a trustee or similar officer for the Borrower and/or any Guarantor or any substantial part of the Borrower or any Guarantor's Property (as defined in the Credit Agreement), or otherwise, this Junior IP Pledge Agreement, all rights hereunder and the applicable Liens created hereby shall continue to be effective, or be reinstated, until such payments have been made.

(ii) Partial Release of IP Collateral. Provided that no Event of Default shall then exist, each of the Bank Priority Representative and the Hedge Priority Representative shall, in connection with any Disposition of any portion of the IP Collateral (other than Dispositions of IP Collateral between and among Grantors (as defined in the Junior Security Agreement), release from the Lien of this Junior IP Pledge Agreement the IP Collateral or portion thereof Disposed of. For the avoidance of doubt, the Lien of each of the Bank Priority Representative and the Hedge Priority Representative on the IP Collateral shall not be released in connection with the

Disposition of the IP Collateral or any part thereof between and among Grantors (as defined in the Junior Security Agreement) and Pledged Entities that are not Foreign Subsidiaries.

(iii) Property Released by UST Representative. Notwithstanding anything herein to the contrary, to the extent that the IP Collateral or any portion thereof is released from the Lien of the UST Representative (as defined in the Intercreditor Agreement), the Lien of each of the Bank Priority Representative and the Hedge Priority Representative on the IP Collateral or such portion thereof shall be released in accordance with Section 10.13 of the Credit Agreement.

Section 6. Miscellaneous

(a) **Waiver; Amendments in Writing.** None of the terms or provisions of this Junior IP Pledge Agreement may be waived, amended, supplemented or otherwise modified except in accordance with subsection 10.1A of the Credit Agreement.

(b) **Notices.** Except as otherwise expressly permitted by this Junior IP Pledge Agreement, all notices, requests and other communications provided for herein (including, without limitation, any modifications of, or waivers, requests or consents under, this Junior IP Pledge Agreement) shall be given or made in writing (including, without limitation, by telecopy or electronic transmission) delivered to the intended recipient at the "Address for Notices" specified on the signatures pages hereof, beneath each party's name; or, as to any party, at such other address as shall be designated by such party in a written notice to each other party. Except as otherwise provided in this Junior IP Pledge Agreement, all such communications shall be deemed to have been duly given when transmitted by telecopier or electronic transmission or personally delivered or, in the case of a mailed notice, upon receipt, in each case given or addressed as aforesaid.

(c) **Section Headings.** The section and subsection headings used in this Junior IP Pledge Agreement are for convenience of reference only and are not to affect the construction hereof or be taken into consideration in the interpretation hereof.

(d) **Counterparts.** This Junior IP Pledge Agreement may be executed in any number of counterparts, each of which shall be an original, but all of which when taken together shall constitute one and the same instrument and any of the parties hereto may execute this Junior IP Pledge Agreement by signing any such counterpart.

(e) **Junior IP Pledge Agreement Constitutes Security Agreement.** This Junior IP Pledge Agreement shall constitute a security agreement within the meaning of the Uniform Commercial Code.

(f) **GOVERNING LAW. THIS JUNIOR IP PLEDGE AGREEMENT SHALL BE CONSTRUED IN ACCORDANCE WITH THE LAWS OF THE STATE OF NEW YORK, WITHOUT REGARD TO ANY RULE OF CONFLICTS OF LAW (OTHER THAN SECTION 5-1401 OF THE NEW YORK GENERAL OBLIGATIONS LAW) THAT WOULD RESULT IN THE APPLICATION OF THE SUBSTANTIVE LAW OF ANY JURISDICTION OTHER THAN THE STATE OF NEW YORK. NOTHING IN THIS AGREEMENT SHALL REQUIRE ANY UNLAWFUL ACTION OR INACTION BY EITHER PARTY.**

(g) **Hypothecation or Pledge of IP Collateral.** Nothing in this Junior IP Pledge Agreement shall preclude the Bank Priority Representative or the Hedge Priority Representative from engaging in repurchase transactions with the IP Collateral or otherwise pledging, repledging, transferring, hypothecating, or rehypothecating the IP Collateral (subject to the interest of the relevant senior secured parties). Nothing contained in this Junior IP Pledge Agreement shall obligate the Bank Priority Representative or the Hedge Priority Representative to segregate any IP Collateral delivered to the Bank Priority Representative or the Hedge Priority Representative by the Borrower or any of the Guarantors.

(h) **Severability.** Any provision of this Junior IP Pledge Agreement held to be invalid, illegal or unenforceable in any jurisdiction shall, as to such jurisdiction, be ineffective to the extent of such invalidity, illegality or unenforceability without affecting the validity, legality and enforceability of the remaining provisions thereof; and the invalidity of a particular provision in a particular jurisdiction shall not invalidate such provision in any other jurisdiction. If any provision of this Junior IP Pledge Agreement shall be held invalid or unenforceable (in whole or in part) as against the Borrower or any one or more Guarantors, then this Junior IP Pledge Agreement shall continue to be enforceable against the Borrower and all other Guarantors without regard to any such invalidity or unenforceability.

(i) **Entire Agreement.** This Junior IP Pledge Agreement and the Loan Documents embody the entire agreement and understanding of the parties hereto and supersede any and all prior agreements, arrangements and understandings relating to the matters provided for herein and therein. No alteration, waiver, amendments, or change or supplement hereto shall be binding or effective unless the same is set forth in writing by a duly authorized representative of the Bank Priority Representative and the Hedge Priority Representative. In the event that any provision of this Junior IP Pledge Agreement shall prove to be invalid or unenforceable, such provision shall be deemed to be severable from the other provisions of this Junior IP Pledge Agreement which shall remain binding on all parties hereto.

(j) **WAIVER OF JURY TRIAL; CONSENT TO JURISDICTION AND VENUE; SERVICE OF PROCESS.** Each party hereto hereby irrevocably and unconditionally:

(A) SUBMITS FOR ITSELF AND ITS PROPERTY IN ANY LEGAL ACTION OR PROCEEDING RELATING TO THIS JUNIOR IP PLEDGE AGREEMENT, OR FOR RECOGNITION AND ENFORCEMENT OF ANY JUDGMENT IN RESPECT THEREOF, TO THE EXCLUSIVE GENERAL JURISDICTION OF ANY COURT OF THE STATE AND COUNTY OF NEW YORK, OR IN THE UNITED STATES DISTRICT COURT FOR THE SOUTHERN DISTRICT OF NEW YORK;

(B) CONSENTS THAT ANY SUCH ACTION OR PROCEEDING MAY BE BROUGHT IN SUCH COURTS AND, TO THE EXTENT PERMITTED BY LAW, WAIVES ANY OBJECTION THAT IT MAY NOW OR HEREAFTER HAVE TO THE VENUE OF ANY SUCH ACTION OR PROCEEDING IN ANY SUCH COURT OR THAT SUCH ACTION OR PROCEEDING WAS BROUGHT IN AN INCONVENIENT COURT AND AGREES NOT TO PLEAD OR CLAIM THE SAME;

(C) AGREES THAT SERVICE OF PROCESS IN ANY SUCH ACTION OR PROCEEDING MAY BE EFFECTED BY MAILING A COPY THEREOF BY REGISTERED OR CERTIFIED MAIL (OR ANY SUBSTANTIALLY SIMILAR FORM OF MAIL), POSTAGE PREPAID, TO ITS ADDRESS SET FORTH ON THE SIGNATURE PAGES HEREOF BENEATH EACH PARTY'S NAME, OR IN SECTION 11.02 OF APPENDIX A OF THE LOAN AGREEMENT OR AT SUCH OTHER ADDRESS OF WHICH THE PLEDGEE SHALL HAVE BEEN NOTIFIED; AND

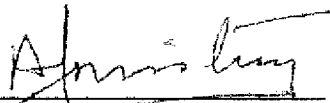
(D) AGREES THAT NOTHING HEREIN SHALL AFFECT THE RIGHT TO EFFECT SERVICE OF PROCESS IN ANY OTHER MANNER PERMITTED BY LAW OR SHALL LIMIT THE RIGHT TO SUE IN ANY OTHER JURISDICTION.

BORROWER AND EACH GUARANTOR HEREBY IRREVOCABLY WAIVES, TO THE FULLEST EXTENT PERMITTED BY APPLICABLE LAW, ANY AND ALL RIGHT TO TRIAL BY JURY IN ANY LEGAL PROCEEDING ARISING OUT OF OR RELATING TO THIS JUNIOR IP PLEDGE AGREEMENT, ANY OTHER LOAN DOCUMENT OR THE TRANSACTIONS CONTEMPLATED HEREBY OR THEREBY.

[SIGNATURE PAGE FOLLOWS]

IN WITNESS WHEREOF, the parties hereto have caused this Junior IP Pledge Agreement to be duly executed and delivered as of the day and year first above written.

GENERAL MOTORS CORPORATION
as Borrower

By: 
Name: Adil Mistry
Title: Assistant Treasurer

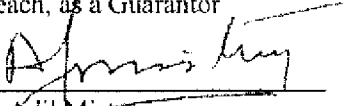
Address for Notices:
767 Fifth Avenue, 14th Floor
New York, NY 10153

Attention: Adil Mistry
Telephone: (212) 418-3507
Facsimile: (212) 418-3695

Signature Page to Intellectual Property Security Agreement

ANNUNCIATA CORPORATION,
ARGONAUT HOLDINGS, INC.,
ENVIRONMENTAL CORPORATE
REMEDICATION COMPANY, INC.,
GENERAL MOTORS ASIA, INC.,
GENERAL MOTORS ASIA PACIFIC
HOLDINGS, LLC,
GENERAL MOTORS OVERSEAS
CORPORATION,
GENERAL MOTORS OVERSEAS
DISTRIBUTION CORPORATION,
GENERAL MOTORS PRODUCT
SERVICES, INC.,
GENERAL MOTORS RESEARCH
CORPORATION,
GM APO HOLDINGS, LLC,
GM EUROMETALS, INC.,
GM FINANCE CO. HOLDINGS LLC,
GM GEFS L.P.,

each, as a Guarantor

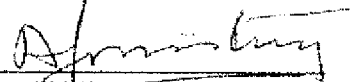
By: 
Name: Adil Mistry
Title: Vice President

Address for Notices:
767 Fifth Avenue, 14th Floor
New York, NY 10153

Attention: Adil Mistry
Telephone: (212) 418-3507
Facsimile: (212) 418-3695

Signature Page to Intellectual Property Security Agreement

GM GLOBAL STEERING HOLDINGS LLC,
GM GLOBAL TECHNOLOGY OPERATIONS,
INC.,
GM GLOBAL TOOLING COMPANY, INC.,
GM LAAM HOLDINGS, LLC,
GM PREFERRED FINANCE CO. HOLDINGS
LLC,
GM SUBSYSTEMS MANUFACTURING LLC,
GM TECHNOLOGIES, LLC,
GM-DI LEASING CORPORATION,
GMOC ADMINISTRATIVE SERVICES
CORPORATION,
GRAND POINTE HOLDINGS, INC.,
ONSTAR, LLC,
REMEDICATION AND LIABILITY
MANAGEMENT COMPANY, INC.,
RIVERFRONT HOLDINGS, INC.,
RIVERFRONT HOLDINGS PHASE II, INC.,
SATURN CORPORATION, and
SATURN DISTRIBUTION CORPORATION,
each, as a Guarantor

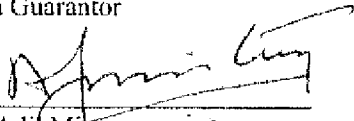
By: 
Name: Adil Mistry
Title: Vice President

Address for Notices:
767 Fifth Avenue, 14th Floor
New York, NY 10153

Attention: Adil Mistry
Telephone: (212) 418-3507
Facsimile: (212) 418-3695

Signature Page to Intellectual Property Security Agreement

**GENERAL MOTORS INTERNATIONAL
HOLDINGS, INC.,**
as a Guarantor

By: 
Name: Adil Mistry
Title: Vice President

Address for Notices:
767 Fifth Avenue, 14th Floor
New York, NY 10153

Attention: Adil Mistry
Telephone: (212) 418-3507
Facsimile: (212) 418-3695

Signature Page to Intellectual Property Security Agreement

CITICORP USA, INC.
as Bank Priority Representative

By: 
Name: _____
Title: **Matthew Paquin**
Vice President

Address for notices:
Citicorp USA, Inc.
Global Loans Support Services
Two Penns Way, Suite 200
New Castle, Delaware 19720
Attention: Carin Seals
Telecopy: 212-994-0961

Signature Page to Intellectual Property Security Agreement

CITICORP USA, INC.
as Hedge Priority Representative

By: 
Name: **Matthew Paquin**
Title: **Vice President**

Address for notices:
Citicorp USA, Inc.
Global Loans Support Services
Two Penns Way, Suite 200
New Castle, Delaware 19720
Attention: Carin Seals
Telecopy: 212-994-0961

Signature Page to Intellectual Property Security Agreement

PATENT
REEL: 022553 FRAME: 0489

Exhibit A

Patents

See attached Exhibits A(1) through (A)(6).

Execution Copy

Exhibit B
Trademarks

See Attached Exhibits B(1) through (B)(7).

Execution Copy

Exhibit C

Copyrights

See attached Exhibits (C)(1) through (C)(3).

Signature Page to Intellectual Property Security Agreement

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PATENT
REEL: 022553 FRAME: 0492